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For Immediate Release

Banpil granted additional optical interconnect patent for its high-speed interconnect technology platform

SANTA CLARA, California, December 1, 2012 -- Banpil Photonics, Inc., a leading company expanding the boundaries of optics and electronics through innovations, today announced that it has been awarded US Patent 8,319,230 that covers optical interconnects technology. The latest patent increases the total number to 21 in the company's overall interconnects patent portfolio, which includes both optical and electrical interconnects, making up its power-efficient, high-speed interconnect platform technology for high performance computing and communications applications.

In current and future IT environments, the demand for higher speeds (also referred to as high-bandwidth) from the smallest devices to computing systems up to global networks, are driven by the increasing higher level of integration within electrical integrated circuits (ICs), with corresponding increases in pin connections per IC, soon to exceed 10,000 interconnections, and higher densities for off-chip interconnections, all demanding novel approaches to be sustainable. More frequently, optical input/output (I/O) is being used in IT systems to transmit data between system components as it is able to attain higher system bandwidth with lower data losses than conventional I/O methods.

Banpil's innovation enables super high-speed electrical and optical interconnects or terabit interconnects for chip-to-chip interconnection necessary for both on-chip and off-chip interconnects to support and sustain current and next-generation IT systems. It has a broad range of applications in computing and communications from broadband portable devices (PC, tablets, and smart phones) to supercomputers, high-speed servers, routers, high-capacity storage systems, data centers, on-demand gaming systems, imaging and networking systems capable of telepresence anywhere on the globe.

An important benefit of the Banpil innovation is that it combines an electrical signal with an optical signal to provide bandwidth greater than that possible with each individual signal. In addition, Banpil's innovation will reduce total cost of ownership (TCO) associated with cooling as it incorporates a sophisticated heat management system directing excess heat from the PCB or chip, so that complex cooling systems that add weight, power and cost can be avoided.

"We are extremely pleased and proud to obtain this new patent. We have already shown the significant performance enhancements that our high-speed interconnects are capable of providing, including 40G and 100G," said Dr. Achyut Dutta, Banpil's CEO. "The patent grant and addition to our portfolio will allows us to now more readily work with other technology companies in joint R&D to develop next generation applications or to license our interconnect portfolio for their own high-speed application product development. Our significant breakthroughs in interconnects will provide licensees and partners a sustainable competitive advantage." The global off-chip PCB market is estimated to exceed $80 billion by 2017 with approximately one third attributed to high-speed PCBs.

Banpil has already demonstrated its high-speed low-power interconnect platform technology. The company welcomes opportunities to work with system vendors and PCB makers to explore new or enhanced applications including joint product development, technology licensing, strategic manufacturing partnerships as well as investors.

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About Banpil Photonics, Inc.

Banpil Photonics is expanding the boundaries of optics and electronics through innovations. Banpil develops and manufactures next generation multispectral image sensors for automotive & medical imaging systems, security & surveillance, and machine vision applications; high-efficiency energy harvesting devices for energy applications; and low-power, high-speed electrical interconnects for chip-to-chip, chip-to-board, board-to-board, and rack-to-rack applications in high-performance computing and networking. The company has an extensive IP portfolio of these innovations available for licensing. For more information, visit www.banpil.com.

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